

### Application

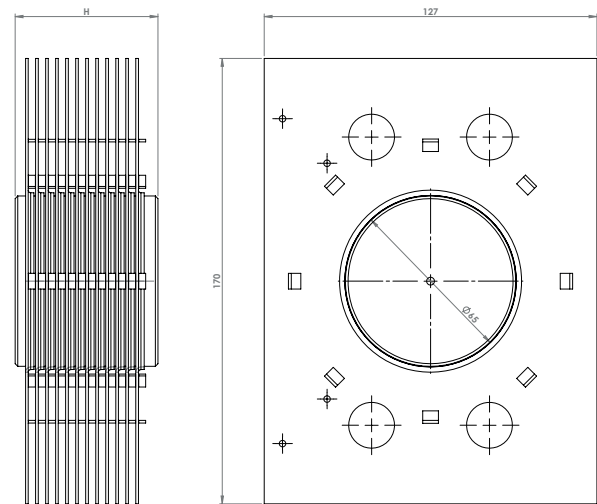
Special Heat Sink for efficient air cooling of Press Pack Disc Semiconductors like Diode, Thyristor, GTO and IGCT Modules.

### General Characteristics

Nickel plated copper heat sink for efficient air cooling of Press Pack Disc Semiconductor. This special type of heat sink is designed for high clamping forces which are required in pressed pack applications.

| Type              | Height H mm | Number of Fins |
|-------------------|-------------|----------------|
| SKL SF-127-170-T1 | 13.5        | 3              |
| SKL 116- L-45     | 27          | 6              |
| SKL 152- L-75     | 40,5        | 9              |
| SKL 201- L-105    | 54          | 12             |

### Drawings



### SKL SF-127-170-T4

